EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	29408	encapsulat$3 same (adhesive epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/09 15:17
L2	66121	("347").CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/09 15:17
L3	382	L1 and L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/09 16:00
L5	587	(347/50).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/09 16:01
S1	1	10/796720	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:32
S2	879	(substratum circuit adj board flex adj circuit PCB TAB tape adj automated adj bond$3) and (cover shroud cap) and (printhead print adj head print$1head) and connector and adhesive and (barrier dam block$4) and contact and (aperture opening hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:11
S4	66075	("347").CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/08 16:42

S5	534	S2 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:42
S6	2941	(347/50,86).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/08 16:43
S7	76	S2 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:43
S8	503	(substratum substrate circuit adj board flex adj circuit PCB TAB tape adj automated adj bond$3) and (cover shroud cap) and connector same (adhesive encapsulate epoxy) same (barrier dam block$4) and contact and (aperture opening hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:18
S9	8	S4 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:14
S10	3314	(substratum substrate circuit adj board flex adj circuit PCB TAB tape adj automated adj bond$3) and (cover shroud cap) and connector same (adhesive encapsulate epoxy) and (barrier dam block$4) and contact and (aperture opening hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:19
S11	122	S4 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:20
S12	14720	(substratum substrate circuit adj board flex adj circuit PCB TAB tape adj automated adj bond$3) and (cover shroud cap) and connector and (adhesive encapsulate epoxy) and (barrier dam block$4) and contact and (aperture opening hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:20

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S13	792	S4 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:21
S14	110	S6 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:20
S15	101	S11 not S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:20
S16	716	S13 not S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:21
S17	691	S13 not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:27
S18	357	S17 not silverbrook.inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 17:27